

Product Change Notice

Micron PCN: 30838 Date: 3/1/2013

Type of Change:	Manufacturing Process Change	
Title of Change:	Broad Market e•MMC 2GB and 4GB Firmware and Manufacturing Changes	
Description of Change:	Broad Market <i>e</i> •MMC 2GB and 4GB parts will be manufactured with the following changes:	
	 New controller version, PS8200FF, will improve the power-on circuit's margin at < -30°C. New Firmware. New substrate design will improve signal integrity. 	
	 Fabrication of the NAND di 	e (L72A) will move to Manassas, VA (FAB6).
Reason for Change:	Optimization of Manufacturing Efficiency	
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Product Affected: Broad	Market e•MMC 2GB (J53K), 4GB	(J54K)
Afi	fected Micron Part Numbers	Replacement Part Numbers
	MTFC2GMVEA-0M WT	MTFC2GMDEA-0M WT
	MTFC4GMVEA-1M WT	MTFC4GMDEA-1M WT
	MTFC4GMVEA-4M IT	MTFC4GMDEA-4M IT
Method of Identification:		gister change from "3.x" to "4.x" will identify new
Micron Sites Affected:	Fabrication — FAB2 (Lehi, UT, US), FAB6 (Manassas, VA, US) Assembly — Subcontractor	
Product/Data Availability	1	
New Production: Sample Availability Qual Data Availab	ility: Aug 2013	
Production Shipme	0/110. 00pt 2010	
	ond. 00pt 2010	
Production Shipme	Nov 2013	
Production Shipme		

Orders placed prior to the LTB date are subject to current inventory levels, which may vary based on market conditions and customer demand. Early orders are encouraged.

Note: Per JEDEC Standard JESD46-C Section 3.2.3; lack of acknowledgment of this PCN within 30 days constitutes acceptance of change